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Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-06-30
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BZMQ*B6AA94Z	A	BO2A	2014-06-30
Amount	UoM	Unit type	ST ECOPACK Grade	
153.60	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3,9,9,9,1.25	16	gull wing	
Comment	SO 16 .15 TO JEDEC MS-012; MD valid for CP: M41T94MQ6F.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BZMQ*B6AA94Z					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	8.408	mg	supplier	die	Silicon (Si)	7440-21-3		8.246	mg	980733	53685
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	2617	143
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1070	59
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	357	20
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.016	mg	1903	104
die (s)				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0.058	mg	6898	378
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.036	mg	4282	234
die (s)				supplier	passivation	Polyhydroxamide	55295-98-2		0.016	mg	1903	104
die (s)				supplier	passivation	Alcoxysilane	proprietary		0.001	mg	119	7
die (s)				supplier	passivation	Aryl Silicic Acid	proprietary		0.001	mg	119	7
Leadframe	Copper & its alloys	31.551	mg	supplier	alloy	Copper (Cu)	7440-50-8		30.624	mg	970619	199375
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.72	mg	22820	4688
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.043	mg	1363	280
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.038	mg	1204	247
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.117	mg	3708	762
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	158	33
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	127	26
Die attach	Other inorganic materials	0.862	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.664	mg	770302	4323
Die attach				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.195	mg	226218	1270
Die attach				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobu	6846-50-0		0.003	mg	3480	20
Bonding wire	Other inorganic materials	0.26	mg	supplier	wire	Gold (Au)	7440-57-5		0.26	mg	1000000	1693
encapsulation	Other Organic Materials	112.519	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		11.032	mg	98046	71823
encapsulation				supplier	mold compound	phenol resin	9003-35-4		5.515	mg	49014	35905
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		1.103	mg	9803	7181
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		88.251	mg	784321	574551
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		2.206	mg	19606	14362
encapsulation				JIG I	mold compound	Brominated epoxy resin	68928-70-1		2.206	mg	19606	14362
encapsulation				JIG I	mold compound	Brominated epoxy resin	68928-70-1		2.206	mg	19606	14362